

Small Signal Schottky diode

RB521S-30C2

Description

Planar silicon Schottky barrier diode encapsulated in a SOD-523 plastic SMD package.

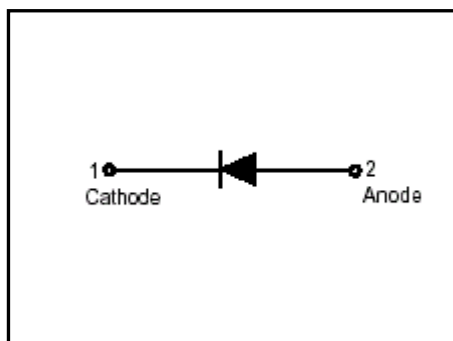
Features

- Extremely small surface mounting type.(SC-79/SOD523)
- $I_o=200\text{mA}$ guaranteed despite the size.
- Low V_F .($V_F=0.4\text{V}$ typ. at 200mA)

Applications

Low current rectification and high speed switching

Symbol



Outline



Absolute Maximum Ratings

- Maximum Temperatures

Storage Temperature	T_{stg}	$-45\sim+125^{\circ}\text{C}$
Junction Temperature	T_j	$+125^{\circ}\text{C}$
- Maximum Voltages and Currents ($T_a=25^{\circ}\text{C}$)

DC Reverse Voltage	V_R	30 V
Mean Rectifying Current	I_F	200 mA
Peak Forward Surge Current	I_{FSM}	1 A

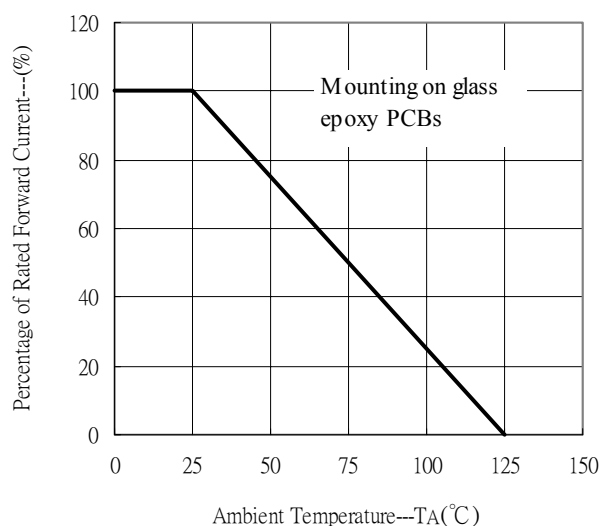


Characteristics (Ta=25°C)

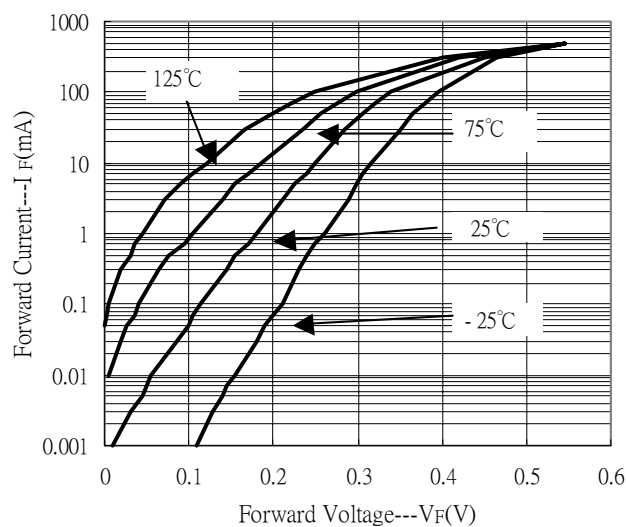
Characteristic	Symbol	Condition	Min.	Max.	Unit
Forward Voltage	V _F	I _F =200mA	-	500	mV
Reverse Leakage Current	I _R	V _R =10V	-	30	μA

Characteristic Curves

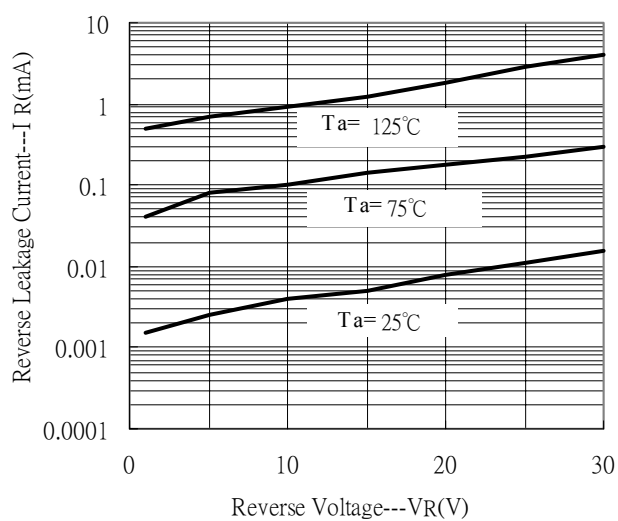
Forward Current Derating Curve



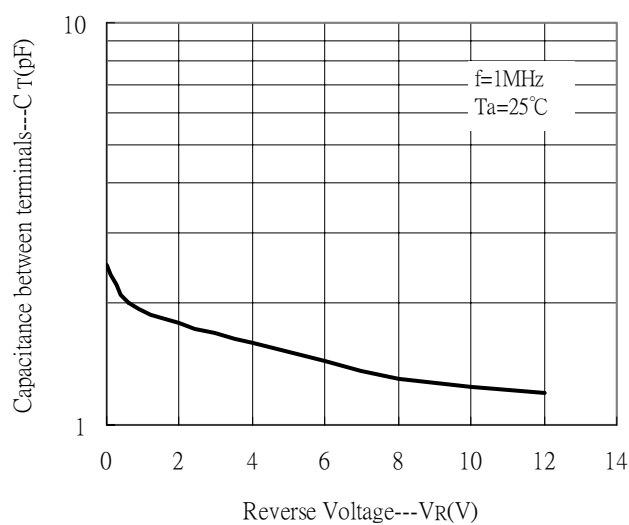
Forward Current vs Forward Voltage



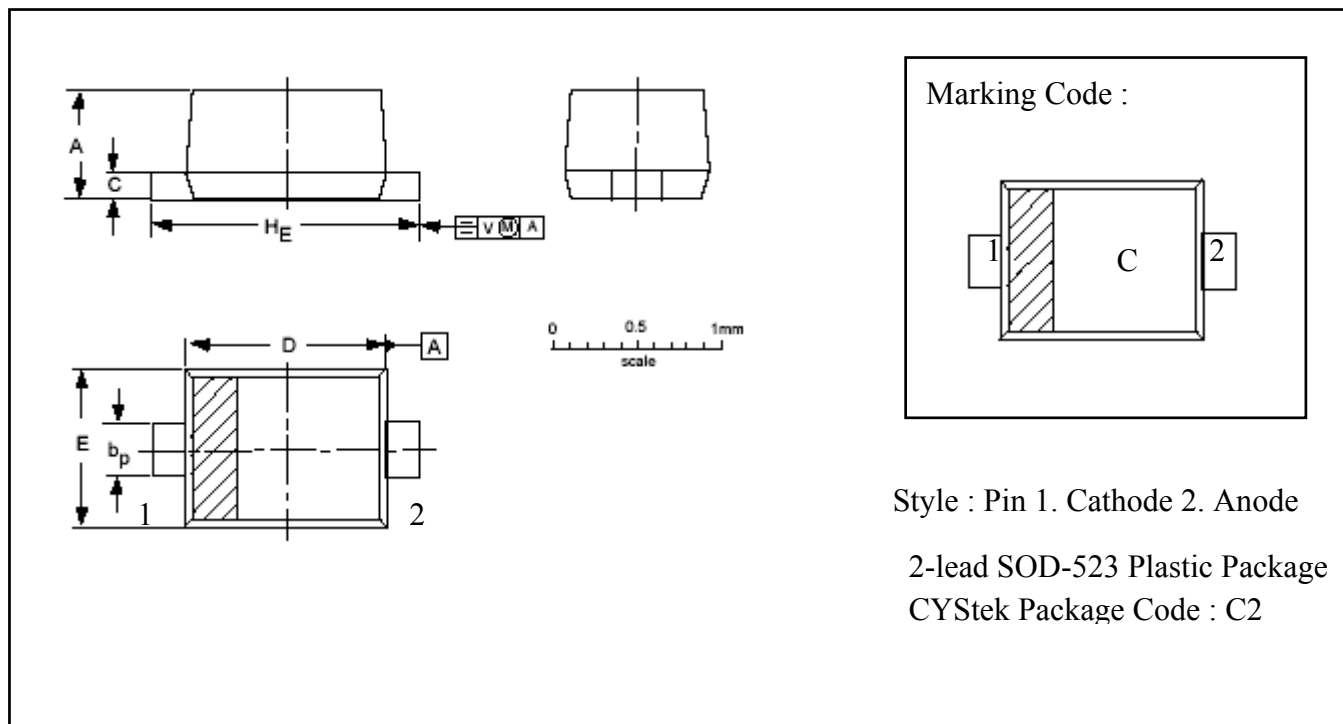
Reverse Leakage Current vs Reverse Voltage



Capacitance vs Reverse Voltage



SOD-523 Dimension



*: Typical

DIM	Millimeters		DIM	Millimeters	
	Min	.Max.		Min.	Max.
A	0.5	0.7	E	0.7	0.9
b _p	0.25	0.35	H _E	1.5	1.7
c	0.1	0.2	V	0.15(typ)	
D	1.1	1.3			

Notes: 1.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
2.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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